

LNPTM THERMOCOMPTM COMPOUND MC004

MC-1004

DESCRIPTION

LNP THERMOCOMP MC004 is a compound based on Polypropylene resin containing Carbon Fiber. Added features of this material include: Electrically Conductive.

TYPICAL PROPERTY VALUES

Revision 20191213

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, break, 5 mm/min	48	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.5	%	ISO 527
Tensile Modulus, 1 mm/min	8100	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	64	MPa	ISO 178
Flexural Stress, break, 2 mm/min	32	MPa	ISO 178
Flexural Modulus, 2 mm/min	7300	MPa	ISO 178
IMPACT			
Izod Impact, unnotched 80*10*4 +23°C	15	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL			
CTE, 23°C to 60°C, flow	3.3E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	1.25E-04	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	129	°C	ISO 75/Af
PHYSICAL			
Mold Shrinkage on Tensile Bar, flow	0.05 – 0.25	%	SABIC method
Density	1	g/cm ³	ISO 1183
ELECTRICAL			
Surface Resistivity	1.E+02 – 1.E+04	Ohm	ASTM D 257
INJECTION MOLDING			
Drying Temperature	80	°C	
Drying Time	4	hrs	
Melt Temperature	225 – 250	°C	
Front - Zone 3 Temperature	240 – 250	°C	
Middle - Zone 2 Temperature	215 – 225	°C	
Rear - Zone 1 Temperature	195 – 205	°C	
Mold Temperature	30 – 50	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	



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